

ABSTRACT

A low-profile package for housing an optoelectronic device is disclosed. The low-profile package includes an insulating base having an upper surface. The optoelectronic device is mounted to the upper surface of the insulating base. The low-profile package also includes a metal sealing member having a top wall and a bottom wall. The bottom wall of the metal sealing member is attached to the upper surface of the insulating base. The low-profile package further includes a substantially flat metal cover attached to the top wall of the metal sealing member to thereby hermetically seal the metal cover to the insulating base.